

WHAT IS CLAIMED IS:

1. A camera module comprising:

an image sensor chip comprising a semiconductor chip having a photoelectronic
transducer formed on a surface of the semiconductor chip and a filter portion disposed on the
photoelectronic transducer so as to block light incident on the filter portion at a predetermined
range of wavelength; and

a lens disposed above the image sensor chip.

2. The camera module of claim 1, wherein the filter portion is configured to provide
mechanical support to the semiconductor chip.

3. The camera module of claim 1, wherein the filter portion comprises a glass plate and
a metal film formed on a surface of the glass plate by vapor deposition.

4. The camera module of claim 1, wherein the filter portion comprises a plastic plate
and a grating formed on a surface of the plastic plate so as to provide a filtering function

5. The camera module of claim 1, wherein the filter portion comprises a glass plate
doped with copper particles or a plastic plate doped with the copper particles.

6. The camera module of claim 1, wherein the semiconductor chip comprises an
electrode pad disposed on the surface of the semiconductor chip that does not have the
photoelectronic transducer formed thereon.

7. The camera module of claim 6, wherein the image sensor chip comprises a terminal
for external connection disposed on a back surface of the image sensor chip and connected to the
electrode pad.